



MBS Plastic-Encapsulate Bridge Rectifier

MB05S THRU MB10S General Purpose Bridge Rectifier

Features

1A ●I_{F(AV)}

50V-1000V $\bullet V_{RRM}$

High surge current capability

Glass passivated chip

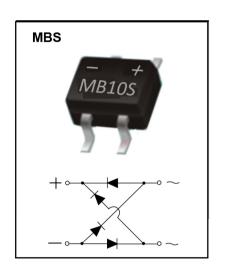
Applications

•General purpose 1 phase Bridge rectifier applications

Marking

MBXXS

X: From 05 To 10



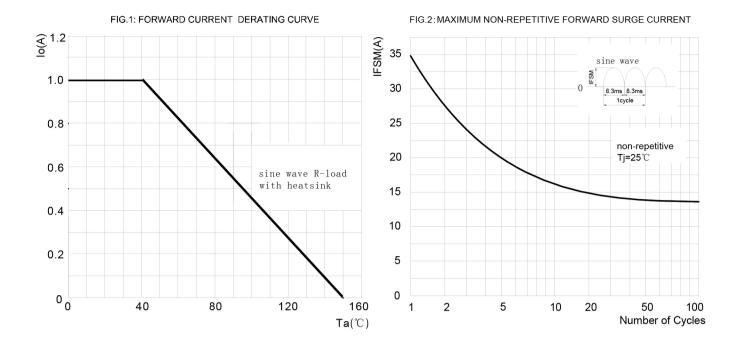
Limiting Values (Absolute Maximum Rating)

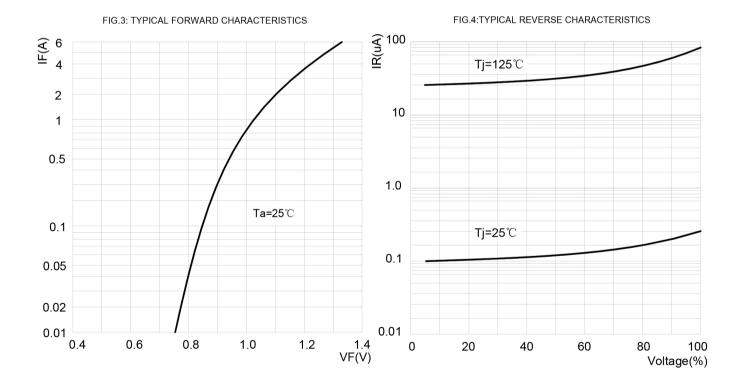
Item	Symbol	Unit	Conditions	МВ						
				05S	18	28	48	68	88	10S
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	V _{RMS}	V		35	70	140	280	420	560	700
Average Rectified Output Current	Io	А	60Hz sine wave, R-load, Ta=40℃	1.0						
Surge(Non- repetitive)Forward Current	I _{FSM}	Α	60H _Z half sine wave, 1 cycle, T _j =25℃	35						
Current Squared Time	l ² t	A ² S	1ms≤t<8.3ms Tj=25℃,Rating of per diode	5.83						
Operation Junction and Storage Temperature Range	T_J, T_stg	$^{\circ}$		-55 ~+150						

Electrical Characteristics $(T_a=25^{\circ}C$ Unless otherwise specified)

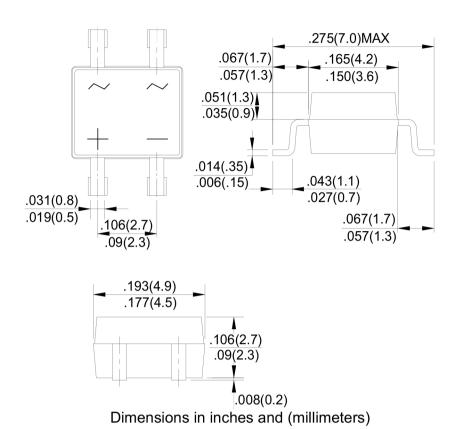
Item	Symbol	Unit	Test Condition	Max	
Peak Forward Voltage	V _{FM}	V	I _{FM} =1.0A, Pulse measurement, Rating of per diode	1.0	
Peak Reverse Current	I _{RRM}	μА	$V_{\text{RM}} = V_{\text{RRM}}$, Pulse measurement, Rating of per diode	10	
Thermal Resistance	R _{d J-A}	°C/W	Between junction and ambient, On alumina substrate	76	
			Between junction and ambient, On glass-epoxi substrate	134	
	R o J-L		Between junction and lead	20	

Typical Characteristics

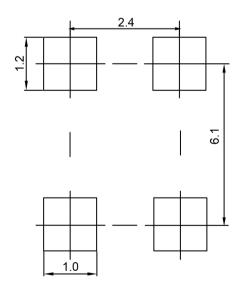




MBS Package Outline Dimensions



MBS Suggested Pad Layout



Note:

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- 1. Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

Reel Taping Specifications For Surface Mount Devices-MBS

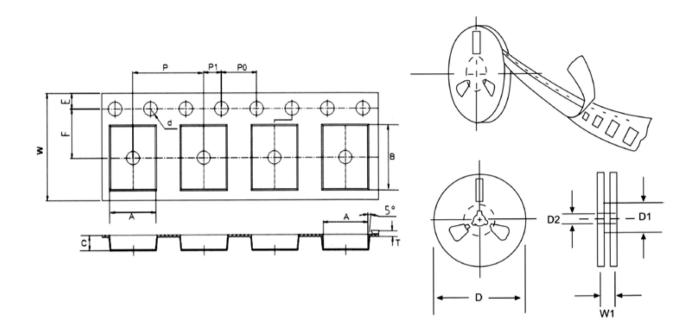


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	MBS mm(inch)
Carrier width	А	5.05+0.1(0.198+0.004)
Carrier length	В	7.22+0.1(0.284+0.004)
Carrier depth	С	2.88+0.1(0.113+0.004)
Sprocket hole	d	1.55±0.05 (0.061±0.002)
Reel outside diameter	D	330±2.0(13±0.079)
Reel inner diameter	D1	75±1.0 (2.95±0.039)
Feed hole diameter	D2	13+0.5(0.512+0.020)
Strocket hole position	E	1.75+0.1(0.069+0.004)
Punch hole position	F	5.50+0.05(0.217+0.002)
Punch hole pitch	Р	8.0+0.1(0.315+0.004)
Sprocket hole pitch	P0	4.0+0.1(0.157+0.004)
Embossment center	P1	2.0+0.1(0.079+0.004)
Totall tape thickness	Т	0.20-0.70(0.080-0.028)
Tape width	W	12.0+0.3/-0.1(0.472+0.004)
Reel width	W1	16.8+2.0(0.661+0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.